

Heat Sink for AMD Kria™ K26 SOM



ATS Part#: **ATS-KRP-3563-C1-R0**
Description: 54 x 68 x 25 mm high-performance heat sink
Component: AMD Kria™ K26 SOM
Heat Sink Type: Passive maxiFLOW heat sink
Heat Sink Attachment: Screws

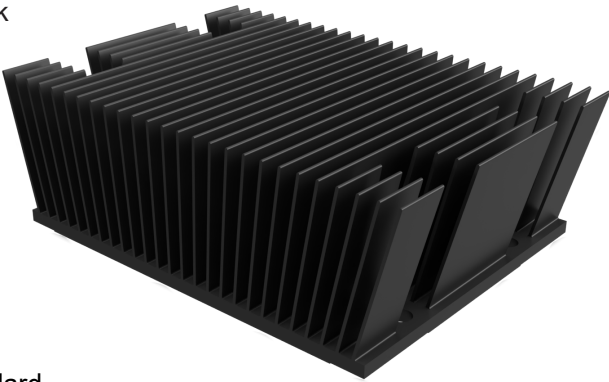


Image for illustration purposes only.

Product Details and Assembly

- » Designed to fit the AMD Kria™ K26 System-on-Module (SOM)
- » Included mounting hardware kit: ATS-HK544-R0
- » Heat sink mounts directly to the heat spreader plate that comes standard on the K26 SOM
- » Provided with pre-assembled Thermal Interface Material (TIM) on base

Heat Sink Part Number	L (mm)	W (mm)	H (mm)	Heat Sink Weight (g)	Thermal Interface Material
ATS-KRP-3563-C1-R0	54	68	25	61	Chomerics T766

Thermal Performance

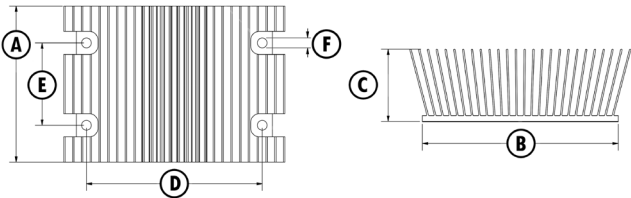
Air Velocity	@100 LFM (0.5 M/S)	@200 LFM (1 M/S)	@300 LFM (1.5 M/S)	@400 LFM (2 M/S)	@500 LFM (2.5 M/S)
Thermal Resistance Ducted Flow	0.88 °C/W	0.58 °C/W	0.48 °C/W	0.43 °C/W	0.40 °C/W

Product Details

SCHEMATIC IMAGE	Dimension A	Dimension B	Dimension C	Dimension D	Dimension E	Dimension F	Material	Finish
	54 mm	68 mm	25 mm	61 mm	28.5 mm	3.4 mm	AL-6063	Black Anodized

NOTES:

- 1) Dimensions A and B refer to heat sink size.
- 2) Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- 3) Dimensions D and E refer to the mounting hole pattern C-C (center to center)
- 4) Dimension F refers to the mounting hole diameter
- 5) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 6) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 7) ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.
- 8) Contact ATS to learn about custom options available.



*All Images are for illustration purposes only.



For further technical information, please contact Advanced Thermal Solutions, Inc.

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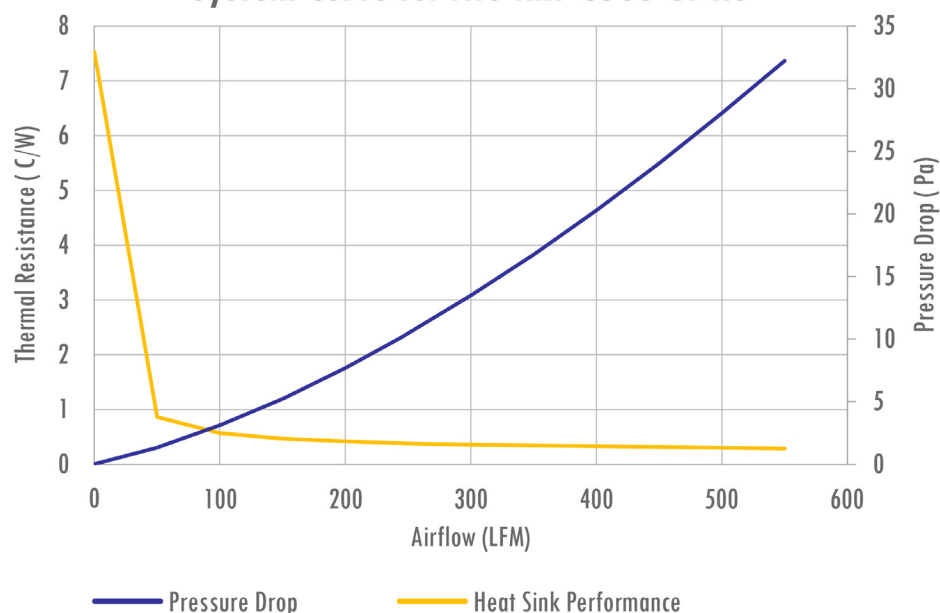
Performance



Adaptive
Computing
Partner

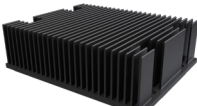
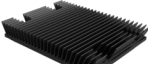
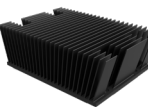
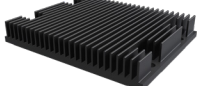
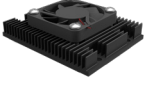
SELECT

System Curve for ATS-KRP-3563-C1-R0



ATS-KRP-3563-C1-R0 Performance	
Air Velocity (LFM)	Thermal Resistance (°C/W)
100	0.88
200	0.58
300	0.48
400	0.43
500	0.40

Heat Sinks for AMD Kria™ K26 SOM

	Heat Sink Type	Heat Sink Part Number	L (mm)	W (mm)	H (mm)	Weight (g)	Thermal Resistance of 1.2 °C/W *
	Passive Straight Fin Heat Sink	ATS-KRP-3559-C1-R0	54	68	20	69	Achieved at 100 LFM
	Passive maxiFLOW Heat Sink	ATS-KRP-3561-C1-R0	54	68	9.76	34	Achieved at 300 LFM
	Passive maxiFLOW Heat Sink	ATS-KRP-3563-C1-R0	54	68	25	61	Achieved at 100 LFM
	Passive Straight Fin Heat Sink	ATS-KRP-3567-C1-R0	54	68	10	44	Achieved at 200 LFM
	Active Straight Fin Heat Sink	ATS-KRA-3559-C1-R0	54	68	20	63	Achieved with fan at 3 CFM
	Active Low Profile Straight Fin Heat Sink	ATS-KRA-3567-C1-R0	54	68	10	45	Achieved with fan at 4 CFM

*Calculated resistance is at 55°C ambient and 15W of total power

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